VACUUM CHUCK TABLE OF SEMICONDUCTOR DEVICE CUTTING APPARATUS CAPABLE OF SUPPLYING COOLING WATER

ABSTRACT

A vacuum chuck table is provided in an apparatus for cutting a semiconductor device molding body and configured to support the semiconductor device molding body. The vacuum chuck table comprises a chuck base, support units adhered to a top surface of the chuck base and configured to support the semiconductor device molding body, and cooling water supply units configured to supply cooling water. A plurality of vacuum holes is formed in the support units. Air is adsorbed through the vacuum holes and so the semiconductor device molding body is adsorbed to the support units. The cooling water is supplied through the cooling water supply units, thereby removing heat generated when the semiconductor device molding body is cut.

Figure 1A